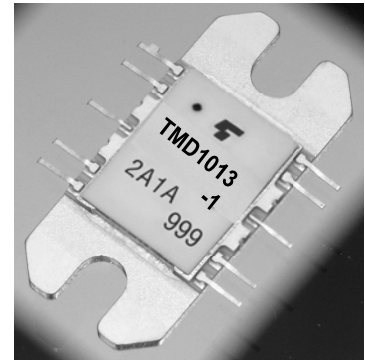


FEATURES

- **BROAD BAND INTERNALLY MATCHED**
- **HIGH POWER**
P1dB= 33.0dBm at 9.5GHz to 12.0GHz
- **HIGH GAIN**
G1dB= 25.0dB at 9.5GHz to 12.0GHz
- **HERMETICALLY SEALED PACKAGE**



RF PERFORMANCE SPECIFICATIONS (Ta= 25°C)

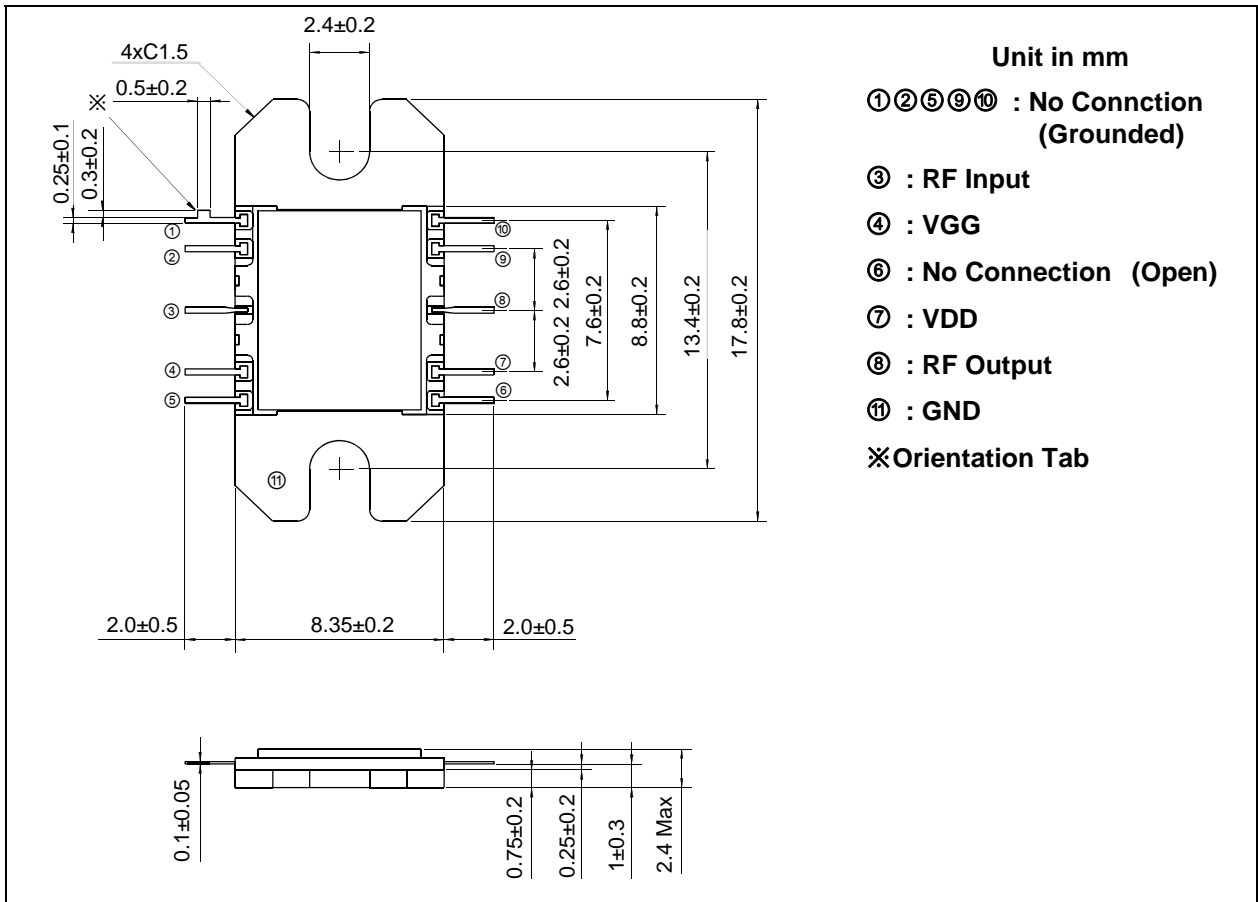
CHARACTERISTICS	SYMBOL	CONDITIONS	UNIT	MIN.	TYP.	MAX.
Output Power at 1dB Gain Compression Point	P1dB	VDD= 10V VGG= -5V f = 9.5 to 12.0GHz	dBm	31.0	33.0	—
Power Gain at 1dB Gain Compression Point	G1dB		dB	21.0	25.0	—
Gain Flatness	ΔG		dB	—	—	±2.5
Drain Current	IDD		A	—	1.4	1.8
Power Added Efficiency	ηadd		%	—	14	—
3rd Order Intermodulation Distortion	IM3	Two-Tone Test Po=19.0dBm, Δf= 5MHz (Single Carrier Level)	dBc	-42	-45	—

ABSOLUTE MAXIMUM RATINGS (Ta= 25°C)

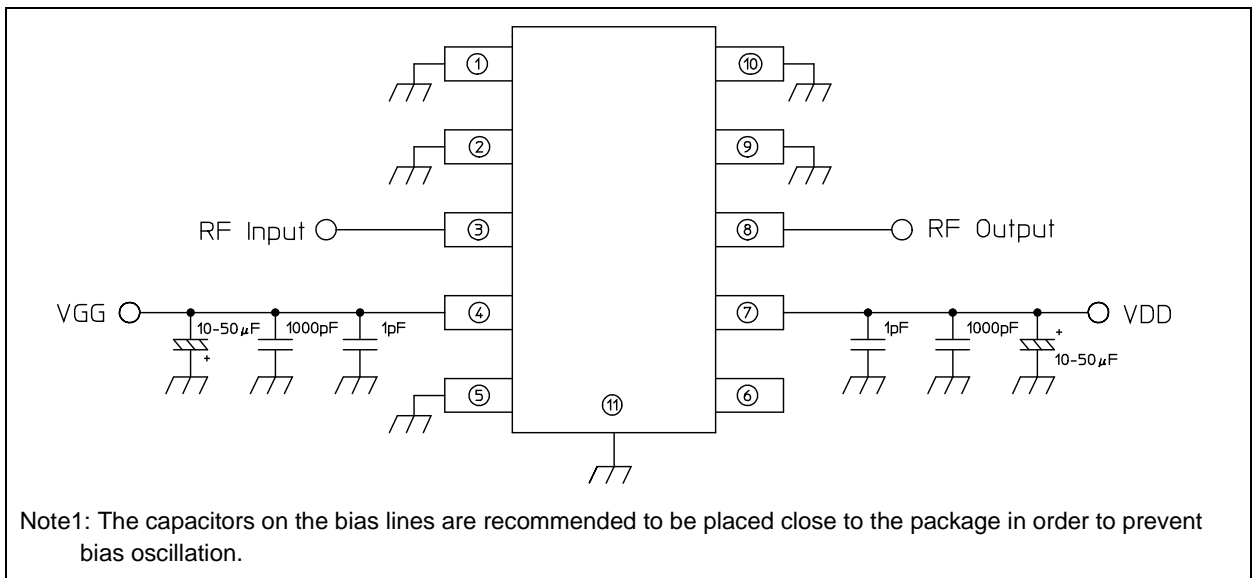
CHARACTERISTICS	SYMBOL	UNIT	MAX.
Drain Supply Voltage	VDD	V	15
Gate Supply Voltage	VGG	V	-10
Input Power	Pin	dBm	15
Flange Temperature	Tf	°C	-30 to +80
Storage Temperature	Tstg	°C	-65 to +175

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PACKAGE OUTLINE (2-9E1D)



RECOMMENDED BIAS CONFIGURATION

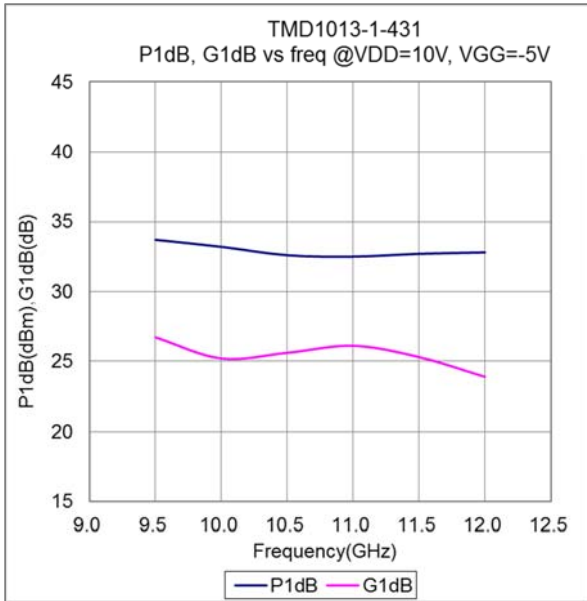


HANDLING PRECAUTIONS FOR PACKAGE MODEL

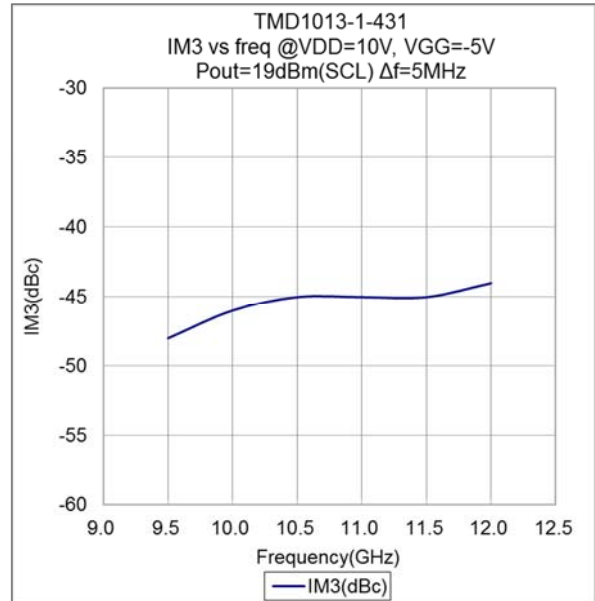
Soldering iron should be grounded and the operating time should not exceed 10 seconds at 260°C or 3 seconds at 350°C. Flanges of devices should be attached using screws and washers. Recommended torque is 0.18-0.20 N·m.

TYPICAL RF PERFORMANCE

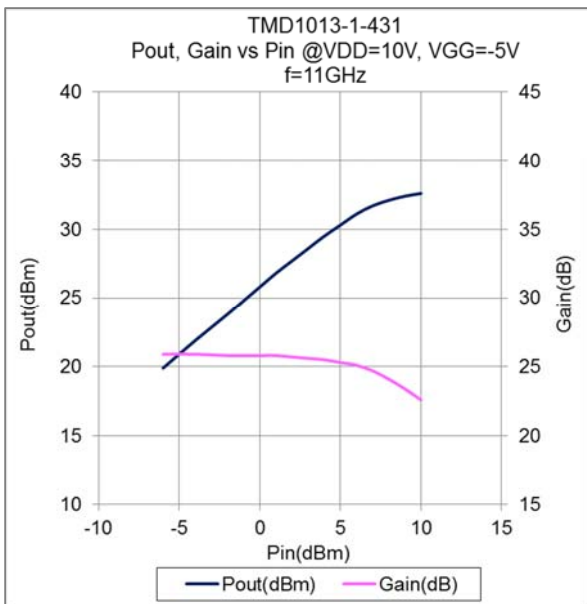
P1dB, G1dB vs. Frequency



IM3 vs. Frequency



Output Power, Gain vs. Input Power



IM3 vs. Output Power

